

# MATERIAL DECLARATION SHEET



Package Type	TBU-PL		
Product Line	Semiconductor Products		
Compliance Date	January 1, 2010		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (Subpart)	Homogeneous Material	Material Weight [g]	Homogeneous Material\ Substances	CAS Number if applicable	Materials Mass %	Material Mass % of Total Unit Weight	Subpart Mass of Total Wt. (%)
1	Encapsulation	Epoxy resin	0.03522	Epoxy Resin	Trade Secret	6	2.776	46.273
				Phenol Resin	Trade Secret	3	1.388	
				Silica fused	60676-86-0	90.45	41.854	
				Carbon Black	1333-86-4	0.55	0.254	
2	Leadframe	Copper alloy	0.0350617	Copper	7440-50-8	96	44.2229	46.066
				Iron	7439-89-6	2.2	1.0134	
				Zinc	7440-66-6	0.1	0.0461	
				Phosphorous	7723-14-0	0.075	0.0345	
				Lead (impurity)	7439-92-1	0.001	0.0005	
				Silver (Plating)	7440-22-4	1.624	0.7481	
3	Chip	Silicon	0.002951	Silicon	7440-21-3	100	3.877	3.877
4	Die Attach	Conductive Silver Epoxy	0.00097	Silver	7440-22-4	93.4	1.190	1.274
				Epoxy resin	Trade Secret	5.5	0.070	
				Polymeric compound	Trade Secret	0.55	0.0070	
				Functionalized Ester	Trade Secret	0.55	0.0070	
5	Bond wires	Gold	0.000462	Gold	7440-57-5	99.99	0.6079	0.608
				Potential impurities may include Ag, Be or Ca ≤ 30 ppm	7440-22-4; 7440-41-7; 7440-70-2	0.01	0.0001	

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6	Terminal Finish	Alloy	0.001448	Tin	7440-31-5	100.00	1.902	1.902
		Total Weight	0.0761127					

Updated January 29, 2019